

3.3V Dual 8-Bit, 40MSPS A/D Converter with Internal Reference and Digital Clamp

The HI2325 is a monolithic, dual 8-bit, 40MSPS analog-to-digital converter fabricated in an advanced CMOS process. It is designed for high speed applications where integration, bandwidth and accuracy are essential. The HI2325 features a 2-stage parallel architecture. Only one external clock is necessary to drive both converters and an internal voltage reference is provided allowing the system designer to realize an increased level of system integration resulting in decreased cost and power dissipation.

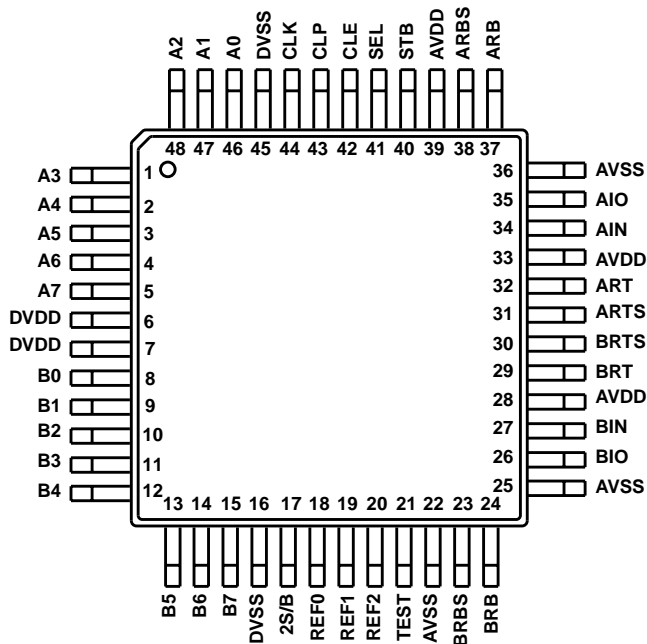
The HI2325 has excellent dynamic performance while consuming less than 100mW power at 40MSPS. The A/D only requires a single +3.3V power supply and encode clock. Data output latches are provided which present valid data to the output bus with a latency of 2 clock cycles.

Ordering Information

| PART NUMBER | TEMP. RANGE (°C) | PACKAGE | PKG. NO. |
|-------------|------------------|-----------------|-----------|
| HI2325IN | -20 to 85 | 48 Ld MQFP/PQFP | Q48.7x7-S |

Pinout

**48 LEAD LQFP
TOP VIEW**



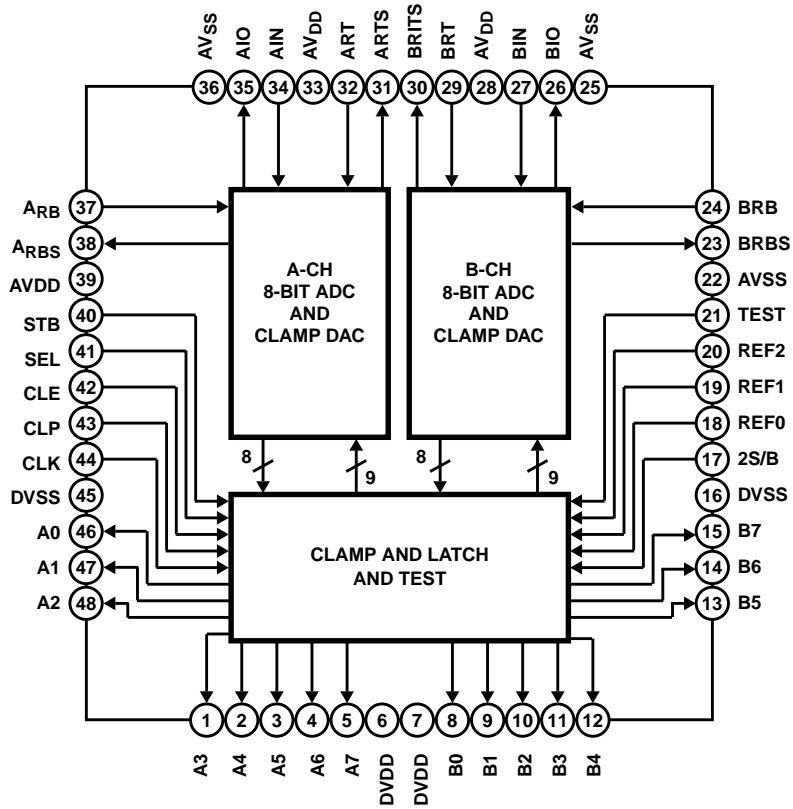
Features

- Sampling Rate40MSPS
- 6.5 Bits at $f_{IN} = 1\text{MHz}$
- Low Power at 40MSPS. 100mW
- Power Down Mode 8mW
- Wide Full Power Input Bandwidth. 250MHz
- Excellent Channel-to-Channel Isolation >75dB
- Internal Digital Clamp
- Internal Voltage Reference
- Single Supply Voltage Operation +3.3V
- TTL/CMOS Compatible Digital Inputs
- CMOS Compatible Digital Outputs. 3.3V
- Offset Binary or 2's Complement Output Format
- Dual 8-Bit A/D Converters on a Monolithic Chip

Applications

- Wireless Local Loop
- PSK and QAM I&Q Demodulators
- Medical Imaging and Instrumentation
- Portable Communications
- Power Metering
- Hand-Held Data Collection Instruments

Functional Block Diagram



Pin Descriptions

| PIN NO. | SYMBOL | I/O | EQUIVALENT CIRCUIT | DESCRIPTION |
|-----------------|--------------|-----|---------------------------------------|---|
| 46, 47, 48, 1-5 | A0 - A7 | O | | Digital Output. A0(LSB) - A7(MSB) |
| 8 - 15 | B0 - B7 | O | | Digital Output. B0(LSB) - B7(MSB) |
| 6, 7 | DVDD | | | Digital power supply. |
| 16 | DVSS | | | Digital ground. |
| 17 | 2S/B | I | Pull-down resistors are incorporated. | Selects output code. H: 2's Compliment Code L: Binary Code |
| 18, 19, 20 | REF0 ~ 2 | I | Pull-down resistors are incorporated. | Determines the clamp circuit reference data. See the table "Digital Clamp Reference Level". |
| 21 | TEST | I | Pull-down resistors are incorporated. | Normally open. |
| 22, 25 | DVSS | | | Digital ground. |
| 22, 25, 36 | AVSS | | | Analog ground. |
| 23 38 | BRBS ARBS | | | Shorting these pins to AVSS generates voltage of about 0.5V at the BRB and ARB pins. |
| 24 37 | BRB ARB | | | Reference voltage (bottom). |
| 29 32 | BRT ART | | | Reference voltage (top). |
| 30 31 | BRTS ARTS | | | Shorting these pins to AVDD generates voltage of about 2.5V at the BRT and ART pins. |
| 26 35 | BIO AIO | O | | Analog output. The digital clamp circuit comprises a D/A converter whose outputs are available on these pins. |
| 27 34 | BIN AIN | I | | Analog input. |
| 28, 33, 39 | AVDD | | | Analog power supply. |
| 40 | STB | I | Pull-down resistors are incorporated. | Stand-by input. H: Stand-by mode L: Operation mode. |
| 41 | SEL | I | Pull-down resistors are incorporated. | Controls the CLP signal polarity. H: CLP is High active L: CLP is Low active. |
| 42 | CLE | I | Pull-down resistors are incorporated. | Clamp enable input. H: Enable L: Disable. |
| 43 | CLP | I | Pull-down resistors are incorporated. | Clamp pulse input. The polarity can be set to either High or Low by setting SEL. |
| 44 | CLK | I | Pull-down resistors are incorporated. | Clock input. |

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$

| | |
|--|-------------------------|
| Supply Voltage, AV_{CC} or DV_{CC} to AGND or DGND | 4V |
| DGND to AGND | 0.3V |
| Digital I/O Pins | DGND to DV_{CC} |
| Analog I/O Pins | AGND to AV_{CC} |

Operating Conditions

| | |
|-------------------|---|
| Temperature Range | |
| HI2325IN | -40°C to 85°C |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Thermal Information

| | |
|--|---|
| Thermal Resistance (Typical, Note 1) | θ_{JA} ($^\circ\text{C}/\text{W}$) |
| 48 Ld MQFP | 84 |
| Maximum Junction Temperature | 150°C |
| Maximum Storage Temperature Range | -65°C to 150°C |
| Maximum Lead Temperature (Soldering 10s) | 300°C (Lead Tips Only) |

Electrical Specifications $AV_{DD} = DV_{DD} = +3.3\text{V}$; $V_{IN} = 1.50\text{V}$; $f_S = 40\text{MSPS}$ at 50% Duty Cycle; $C_L = 10\text{pF}$; $T_A = 25^\circ\text{C}$; Unless Otherwise Specified

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|---|--|-----|-----------|-----|------------|
| ACCURACY | | | | | |
| Resolution | | 8 | - | - | Bits |
| Integral Linearity Error, INL | $f_{IN} = 1\text{MHz}$ | - | 0.2 | - | LSB |
| Differential Linearity Error, DNL (Guaranteed No Missing Codes) | $f_{IN} = 1\text{MHz}$ | - | ± 0.7 | - | LSB |
| Offset Error, V_{OS} | $f_{IN} = \text{DC}$ | -50 | - | 50 | mV |
| Full Scale Error, FSE | $f_{IN} = \text{DC}$ | - | 1 | - | LSB |
| DYNAMIC CHARACTERISTICS | | | | | |
| Minimum Conversion Rate | No Missing Codes | 1 | - | - | MSPS |
| Maximum Conversion Rate | No Missing Codes | 40 | - | - | MSPS |
| Effective Number of Bits, ENOB | $f_{IN} = 1\text{MHz}$ | - | 6.5 | - | Bits |
| Signal to Noise and Distortion Ratio, SINAD $= \frac{\text{RMS Signal}}{\text{RMS Noise} + \text{Distortion}}$ | $f_{IN} = 1\text{MHz}$ | - | 41 | - | dB |
| Signal to Noise Ratio, SNR $= \frac{\text{RMS Signal}}{\text{RMS Noise}}$ | $f_{IN} = 1\text{MHz}$ | - | 42.5 | - | dB |
| Total Harmonic Distortion, THD | $f_{IN} = 1\text{MHz}$ | - | -46 | - | dBc |
| 2nd Harmonic Distortion | $f_{IN} = 1\text{MHz}$ | - | -48 | - | dBc |
| 3rd Harmonic Distortion | $f_{IN} = 1\text{MHz}$ | - | -52 | - | dBc |
| Spurious Free Dynamic Range, SFDR | $f_{IN} = 1\text{MHz}$ | - | 48.5 | - | dBc |
| Intermodulation Distortion, IMD | $f_1 = 1\text{MHz}$, $f_2 = 1.02\text{MHz}$ | - | - | - | dBc |
| I/Q Channel Crosstalk | | - | -75 | - | dBc |
| I/Q Channel Offset Match | | - | 1.0 | - | LSB |
| I/Q Channel Full Scale Error Match | | - | 0.25 | - | LSB |
| Transient Response | (Note 2) | - | 1 | - | Cycle |
| Over-Voltage Recovery | 0.2V Overdrive (Note 2) | - | 1 | - | Cycle |
| ANALOG INPUT | | | | | |
| Maximum Peak-to-Peak Single-Ended Analog Input Range | | - | 1.0 | - | V |
| Analog Input Resistance, R_{INA} or R_{INB} | V_{INA} , $V_{INB} = V_{REF}$, DC | - | - | - | M Ω |
| Analog Input Capacitance, C_{INA} or C_{INB} | V_{INA} , $V_{INB} = 1.5\text{V}$, DC | - | - | - | pF |

HI2325

Electrical Specifications $A_{VDD} = D_{VDD} = +3.3V$; $V_{IN} = 1.50V$; $f_S = 40MSPS$ at 50% Duty Cycle;
 $C_L = 10pF$; $T_A = 25^{\circ}C$; Unless Otherwise Specified **(Continued)**

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNITS |
|---|--|-------|-------------|-----|-------------------|
| Analog Input Bias Current, I_{BA} or I_{BB} | $V_{INA}/V_{INB} = ART/BRT, ARB/BRB, DC$ (Notes 2, 3) | - | - | - | μA |
| Full Power Input Bandwidth, FPBW | $f_S = 40MHz$, (Note 2) | - | - | - | MHz |
| REFERENCE VOLTAGE INPUT | | | | | |
| Reference Voltage Input Range | | - | - | - | V |
| Total Reference Resistance, R_{RIN} | | - | 370 | - | $k\Omega$ |
| Reference Current, I_{RIN} | | - | 5.4 | - | mA |
| Self Bias | V_{RB} | - | 0.54 | - | |
| | V_{RT} | - | 1.9 | - | |
| SAMPLING CLOCK INPUT | | | | | |
| Input Logic High Voltage, V_{IH} | CLK | 2.0 | - | - | V |
| Input Logic Low Voltage, V_{IL} | CLK | - | - | 0.8 | V |
| Input Logic High Current, I_{IH} | CLK, $V_{IH} = 3.3V$ | - | - | - | μA |
| Input Logic Low Current, I_{IL} | CLK, $V_{IL} = 0V$ | - | - | - | μA |
| Input Capacitance, C_{IN} | CLK | - | - | - | pF |
| DIGITAL OUTPUTS | | | | | |
| Output Logic High Voltage, V_{OH} | $I_{OH} = 100\mu A$; $D_{VDD} = 3.3V$ | - | - | - | V |
| Output Logic Low Voltage, V_{OL} | $I_{OL} = 1.5mA$; $D_{VDD} = 3.3V$ | - | - | - | V |
| Output Logic High Voltage, V_{OH} | $I_{OH} = 100\mu A$; $D_{VDD} = 3.0V$ | - | - | - | V |
| Output Logic Low Voltage, V_{OL} | $I_{OL} = 100\mu A$; $D_{VDD} = 3.0V$ | - | - | - | V |
| Output Capacitance, C_{OUT} | | - | - | - | pF |
| TIMING CHARACTERISTICS | | | | | |
| Aperture Delay, t_{AP} | | - | 4 | - | ns |
| Aperture Jitter, t_{AJ} | | - | 5 | - | ps _{RMS} |
| Data Output Hold, t_H | | - | 10.7 | - | ns |
| Data Output Delay, t_{OD} | | - | 11.7 | - | ns |
| Data Latency, t_{LAT} | For a Valid Sample (Note 2) | 2 | 2 | 2 | Cycles |
| Power-Up Initialization | Data Invalid Time (Note 2) | - | - | - | Cycles |
| Sample Clock Pulse Width (Low) | (Note 2) | 11.25 | 12.5 | - | ns |
| Sample Clock Pulse Width (High) | (Note 2) | 11.25 | 12.5 | - | ns |
| Sample Clock Duty Cycle Variation | | - | ± 5 | - | % |
| POWER SUPPLY CHARACTERISTICS | | | | | |
| Analog Supply Voltage, A_{VDD} | (Note 2) | 3.0 | 3.3 | 3.6 | V |
| Digital Supply Voltage, D_{VDD} | (Note 2) | 3.0 | 3.3 | 3.6 | V |
| Supply Current, I_{DD} | $f_S = 40MSPS$ | - | 30.3 | - | mA |
| Power Dissipation | | - | 100 | - | mW |
| Offset Error Sensitivity, ΔV_{OS} | A_{VDD} or $D_{VDD} = 3.3V \pm 5\%$ | - | ± 0.125 | - | LSB |
| Gain Error Sensitivity, ΔFSE | A_{VDD} or $D_{VDD} = 3.3V \pm 5\%$ | - | ± 0.15 | - | LSB |

NOTES:

2. Parameter guaranteed by design or characterization and not production tested.
3. With the clock low and DC input.

TABLE 1. OUTPUT MODE

| INPUT | | | OUTPUT | | | | | | | |
|-------|-----|------|---------------------|----------|----------|----------|----------|----------|----------|----------|
| TEST | STB | 2S/B | A7 B7 | A6 B6 | A5 B5 | A4 B4 | A3 B3 | A2 B2 | A1 B1 | A0 B0 |
| L | L | L | Binary Code | | | | | | | |
| L | L | H | 2's Compliment Code | | | | | | | |
| L | H | X | Hi-Z | | | | | | | |
| H | X | X | Test Mode | | | | | | | |

TABLE 2. DIGITAL OUTPUT

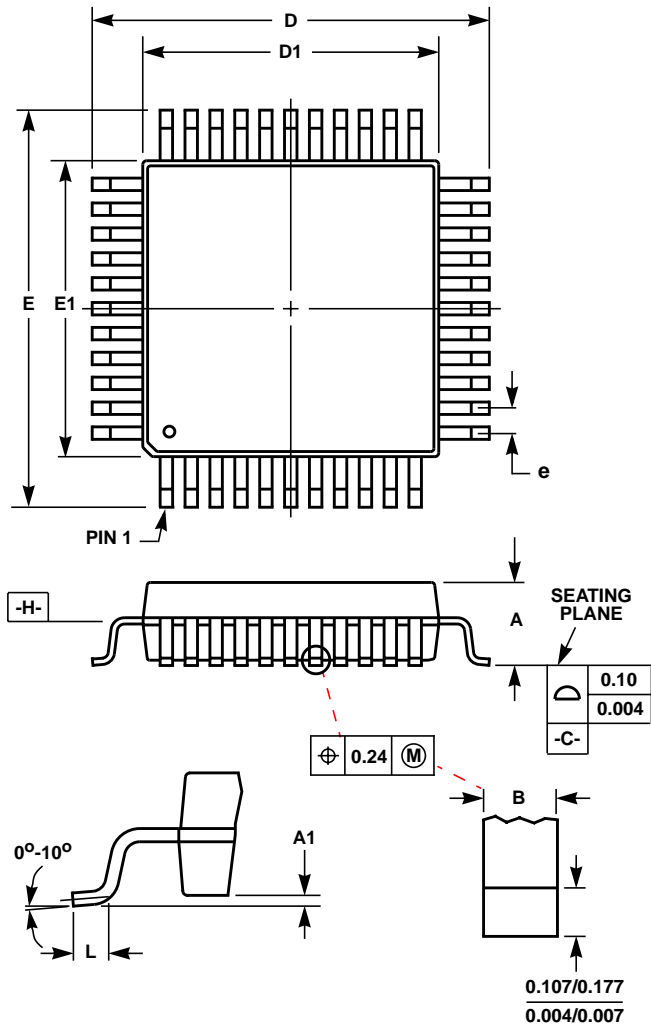
The following table shows the relationship between analog input voltage and digital output code.

| INPUT SIGNAL VOLTAGE | STEP | DIGITAL OUTPUT CODE | | | |
|----------------------|------|---------------------|-----|---------------------|-----|
| | | BINARY CODE | | 2's COMPLIMENT CODE | |
| | | MSB | LSB | MSB | LSB |
| VART, VBRT | 255 | 11111111 | | 01111111 | |
| : | : | : | | : | |
| : | 128 | 10000000 | | 00000000 | |
| : | 127 | 01111111 | | 11111111 | |
| : | : | : | | : | |
| VARB, VBRB | 0 | 00000000 | | 10000000 | |

TABLE 3. DIGITAL CLAMP REFERENCE LEVEL

| SETTING | | | REFERENCE LEVEL | | | |
|---------|------|------|-----------------|---------|----------|----------------|
| REF2 | REF1 | REF0 | MODE | DECIMAL | BINARY | 2's COMPLIMENT |
| L | L | L | 0 | 1 | 00000001 | 10000001 |
| L | L | H | 1 | 16 | 00010000 | 10010000 |
| L | H | L | 2 | 32 | 00100000 | 10100000 |
| L | H | H | 3 | 128 | 10000000 | 00000000 |
| H | L | L | 4 | 254 | 11111110 | 01111110 |
| H | L | H | 5 | 239 | 11101111 | 01101111 |
| H | H | L | 6 | 223 | 11011111 | 01011111 |
| H | H | H | 7 | 127 | 01111111 | 11111111 |

Metric Plastic Quad Flatpack Packages (MQFP/PQFP)



Q48.7x7-S

48 LEAD METRIC PLASTIC QUAD FLATPACK PACKAGE

| SYMBOL | INCHES | | MILLIMETERS | | NOTES |
|--------|-----------|-------|-------------|------|-------|
| | MIN | MAX | MIN | MAX | |
| A | 0.056 | 0.066 | 1.40 | 1.70 | - |
| A1 | 0.000 | 0.007 | 0.00 | 0.20 | - |
| B | 0.006 | 0.010 | 0.15 | 0.26 | 5 |
| D | 0.347 | 0.362 | 8.80 | 9.20 | 2 |
| D1 | 0.272 | 0.279 | 6.90 | 7.10 | 3, 4 |
| E | 0.347 | 0.362 | 8.80 | 9.20 | 2 |
| E1 | 0.272 | 0.279 | 6.90 | 7.10 | 3, 4 |
| L | 0.012 | 0.027 | 0.30 | 0.70 | - |
| N | 48 | | 48 | | 6 |
| e | 0.020 BSC | | 0.500 BSC | | - |

Rev. 1 4/95

NOTES:

1. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.
2. Dimensions D and E to be determined at seating plane -C-.
3. Dimensions D1 and E1 to be determined at datum plane -H-.
4. Dimensions D1 and E1 do not include mold protrusion.
5. Dimension B does not include dambar protrusion.
6. "N" is the number of terminal positions.

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